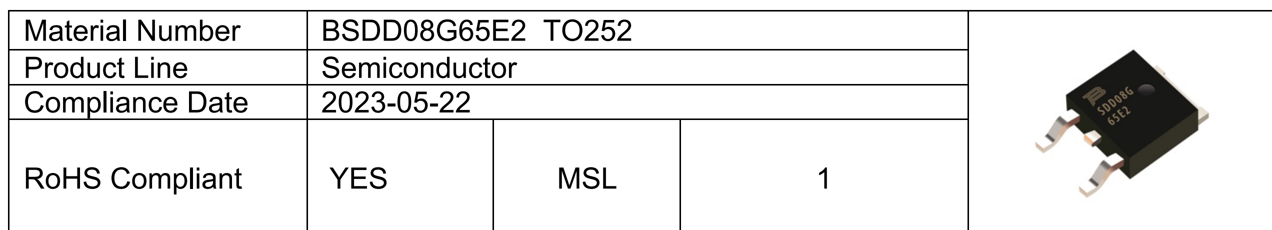
MATERIAL DECLARATION SHEET



Material Number	BSDD08G65E2 TO252		
Product Line	Semiconductor		
Compliance Date	2023-05-22		
RoHS Compliant	YES	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	1.07	Silicon Carbide (SiC)	409-21-2	100	0.235	0.235
2	Die Attach	Die Attach	0.05	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.011	0.209
			0.9	Silver (Ag)	7440-22-4	95	0.198	
3	Lead Frame	Copper alloy	0.05	Phosphorous (P)	7723-14-0	0.03	0.011	38.313
			0.05	Nickel (Ni)	7440-02-0	0.03	0.011	
			0.17	Iron (Fe)	7439-89-6	0.1	0.037	
			173.92	Copper (Cu)	7440-50-8	99.84	38.254	
4	Mold Compound	Resin	10.09	Phenol Formaldehyde resin (generic)	9003-35-4	3.8	2.219	58.412
			15.93	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6	3.504	
			239.02	Silica fused	60676-86-0	90	52.572	
			0.53	Carbon black	1333-86-4	0.2	0.117	
5	Plating	Tin plating	12	Tin (Sn)	7440-31-5	100	2.639	2.639
6	Wire	Pure metal	0.87	Aluminium (Al)	7429-90-5	100	0.191	0.191
		Total weight	454.65 mg					

This Document was updated on: 2023/05/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society